

MODULAR BUILDING

OUR NEXT BIG THING BLOCK



Key Advantages

- » Modular Design to Create Multiple Systems
- » Reusable Modules for Maximum Compatibility
- » Support Enterprise EIA 19" & ORv3 Racks
- » Rack-integrated Liquid Cooling Solution



Truly Flexible Systems



Faster Time-to-Market Solution



Easy Future Scalability



Air & Liquid Cooling Solutions



Customized Modules

	SV1120I	SV1121I
Form Factor	1 RU	1 OU
HPM/ Motherboard	Intel Eagle Stream Platform	
Processor	2 x 4th Gen Intel® Xeon® Scalable Processors	2 x 4th Gen Intel® Xeon® Scalable Processors
Memory	$32 \times DDR5$ RDIMMs, 16 Channels, up to 4800 MT/s at 1DPC, 4400 MT/s at 2DPC 2 x E3.S CXL Memory Modules (SKU 3 & 4)	
Storage	SKU 1: 24 x E1.S SSDs SKU 2: 12 x U.2 NVMe SSDs SKU 3: 16 x E1.S SSDs SKU 4: 8 x U.2 NVMe SSDs	SKU 1: 12 x E1.S SSDs SKU 2: 6 x E1.S SSDs SKU 3: 6 x E1.S SSDs
	2 x 22110 M.2 Boot Drives	
Expansion Slots	2 x PCIe 5.0 x16 FHHL Slots 1 x PCIe 5.0 x16 OCP NIC 3.0	SKU 1 & 3: • 2 x PCle 5.0 x16 FHHL Slots • 1 x PCle 5.0 x16 OCP NIC 3.0 SKU 2: • 2 x PCle 5.0 x16 FHHL Slots • 2 x PCle 5.0 x16 FHHL Slots • 1 x PCle 5.0 x16 OCP NIC 3.0
I/O Ports	1 x 1GbE/RJ45 Management Port 1 x USB 2.0 1 x Mini Display Port 1 x Reset Button 1 x Power Button with LED 1 x UID Button with LED	
PSUs	2 x 2400W Platinum Redundant (1+1) PSU	Centralized 48V Bus Bar with PDB
Security & Management	DC-SCM 1.0 (Root of Trust, TPM, AST2600 BMC)	
Cooling Solution	8 x 4056 Dual Rotor System Fans(N+1 Redundant)	Air: CPU Remote Heatsink, 11 x 4056 Dual Rotor System Fans(N+1 Redundant) Liquid: CPU Cold-Plates to Rack Quick-Disconnects, 6 x 4056 Dual Rotor System Fans (N+1 Redundant)
Chassis Dimension (H x W x D)	1.71" x 17.32" x 31.8" / 43.4mm x 440.0mm x 807.8mm	1.83" x 20.47" x 31.4" / 46.5mm x 520.0mm x 798.0mm